

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YING-RU SHIH	07/02/2021
	WEI LI WU	07/02/2021
	HUNG-CHANG LO	06/29/2021
RECEIVING PARTY DATA		
Name:	GLOBALWAFERS CO., LTD.	
Street Address:	NO. 8, INDUSTRIAL EAST ROAD 2, SCIENCE-BASED INDUSTRIAL PARK,	
City:	HSINCHU	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	17368845
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	099458-US-PA	
NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	
DATE SIGNED:	07/16/2021	
Total Attachments: 3		
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source=099458_asm#page3.tif		

ASSIGNMENT

WHEREAS,

1.Ying-Ru Shih
3.Hung-Chang Lo

2.Wei Li Wu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **BONDING WAFER STRUCTURE AND METHOD OF MANUFACTURING THE SAME**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. GlobalWafers Co., Ltd.
of No. 8, Industrial East Road 2, Science-Based Industrial
Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ying-Ru Shih Date: 02 JUL 2021
Sole or First Joint Inventor: **Ying-Ru Shih**

Signature: Wei Li Wu Date: 02 JUL 2021
Second Joint Inventor (if any): **Wei Li Wu**

Signature: _____ Date: _____
Third Joint Inventor (if any): **Hung-Chang Lo**

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: _____ Date: _____

Sole or First Joint Inventor: **Ying-Ru Shih**

Signature: _____ Date: _____

Second Joint Inventor (if any): **Wei Li Wu**

Signature: Hung-Chang Lo Date: 2021.6.29

Third Joint Inventor (if any): **Hung-Chang Lo**